

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Currently amended) An electronic device, located in surroundings providing an initial airflow, comprising:

a host, comprising a housing and a circuit having at least one first heat source and at least one second heat source disposed in the housing;

a display unit electronically connected to the circuit; and

a heat-dissipating module for providing heat transfer and convection to the surroundings, having at least one conductive assembly disposed on the first heat source to absorb heat transferring from the first heat source and at least one first fan assembly located between the surroundings and the conductive assembly, wherein the first fan assembly introduces the initial airflow of the surroundings into the conductive assembly to form at least one first airflow, and the first airflow passes the second heat source having temperature higher than that of the first airflow to form at least one second airflow, and temperature ingredient is yielded between the first airflow and the second airflow.

2. (Currently amended) The electronic device as claimed in claim 1, wherein temperature of the first heat source is higher than ~~does not exceed~~ that of the second heat source.

3. (Original) The electronic device as claimed in claim 1, wherein the first fan assembly is disposed near one side of the housing.

4. (Original) The electronic device as claimed in claim 1, wherein the housing comprises an inlet, and the first fan assembly is disposed between the inlet and the conductive assembly.

5. (Original) The electronic device as claimed in claim 1, wherein the conductive assembly comprises a heat-transfer unit connected to the first heat source.

6. (Original) The electronic device as claimed in claim 5, wherein the heat-transfer unit comprises a fin structure.

7. (Original) The electronic device as claimed in claim 1, wherein the first heat source comprises a CPU.

8. (Original) The electronic device as claimed in claim 1, wherein the second heat source comprises a memory module.

9. (Original) The electronic device as claimed in claim 1, further comprising a conductive pipe transferring heat from the conductive assembly to one side of the first fan assembly.

10. (Original) The electronic device as claimed in claim 3, further comprising a second fan assembly disposed on one side of the housing conducting the second airflow to the surroundings.

11. (Cancelled).

12. (Currently amended) A heat-dissipating module for providing heat transfer and convection on at least one first heat source and at least one second heat source located in a housing by an initial airflow of a surroundings, comprising:

at least one conductive assembly disposed on the first heat source to absorb heat transferring from the first heat source;

at least one first fan assembly located between the surroundings and the conductive assembly, wherein the first fan assembly introduces the initial airflow of the surroundings into the conductive assembly to form at least one first airflow, and the first airflow passes the second heat source having temperature higher than that of the first airflow to form at least one second airflow, and temperature ingredient is yielded between the first airflow and the second airflow.

13. (Currently amended) The heat-dissipating module as claimed in claim 12, wherein temperature of the first heat source is higher than ~~does not exceed~~ that of the second heat source.

14. (Cancelled)

15. (Original) The electronic device as claimed in claim 12, wherein the housing comprises an inlet, and the first fan assembly is disposed between the inlet and the conductive assembly.

16. (Original) The electronic device as claimed in claim 12, wherein the conductive assembly has a heat-transfer unit connected to the first heat source.

17. (Original) The electronic device as claimed in claim 12, wherein the first heat source comprises a CPU.

18. (Original) The electronic device as claimed in claim 12, wherein the second heat source comprises a memory module.

19. (Original) The electronic device as claimed in claim 12, further comprising a conductive pipe transferring heat from the conductive assembly to one side of the first fan assembly.

20. (Original) The electronic device as claimed in claim 12, further comprising a second fan assembly disposed on one side of the housing conducting the second airflow to the surroundings.